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Product Change Notification - JAON-17JDSD193

Date: 05 Aug 2016

Product Category: Analog (Thermal, Power Management & Safety)

Notification subject: CCB 2596 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond

wire in selected products of the 40K wafer technology available in 8L MSOP package at MTAI

assembly site.

Notification text: PCN Status: Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K wafer technology available in 8L MSOP package at MTAI assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 4, 2016 (date code: 1635)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2016			July 2016			August 2016				September 2016							
WW	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39
Initial PCN Issue Date		Х																
Qual Report Availability										Х								
Final PCN Issue Date										Х								
Estimated Implementation Date														Х				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

June 9, 2016: Issued initial notification.

August 5, 2016: Issued final notification. Attached the qualification report. Provided estimated first ship date on September 4, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): PCN_JAON-17JDSD193_Qual_Report.pdf

PCN_JAON-17JDSD193_Affected_CPN.pdf PCN_JAON-17JDSD193_Affected_CPN.xls

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Affected Catalog Part Numbers (CPN)

PCN JAON-17JDSD193
CATALOG PART NBR
TC1410EUA
TC1410EUA713
TC1410NEUA
TC1410NEUA713
TC1410NVUA
TC1410NVUA713
TC1411EUA
TC1411EUA713
TC1411NEUA
TC1411NEUA713
TC1411NVUA
TC1411NVUA713
TC1411VUA
TC1411VUA713
TC1412EUA
TC1412EUA713
TC1412NEUA
TC1412NEUA713
TC1413EUA
TC1413EUA713
TC1413NEUA
TC1413NEUA713
TC1426CUA
TC1426CUA713
TC1427CUA
TC1427CUA713
TC1428CUA
TC1428CUA713
TC426CUA
TC426CUA713
TC426EUA
TC426EUA713
TC427CUA
TC427CUA713
TC427EUA
TC427EUA713
TC428CUA
TC428CUA713
TC428EUA
TC428EUA713
TC4426ACUA
TC4426ACUA713
TC4426AEUA

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Affected Catalog Part Numbers (CPN)

PCN_JAON-17JDSD193
CATALOG_PART_NBR
TC4426AEUA713
TC4426AVUA
TC4426AVUA713
TC4426CUA
TC4426CUA713
TC4426EUA
TC4426EUA713
TC4426VUA
TC4426VUA713
TC4427AEUA
TC4427AEUA713
TC4427AVUA
TC4427AVUA713
TC4427CUA
TC4427CUA713
TC4427EUA
TC4427EUA713
TC4427VUA
TC4427VUA713
TC4428AEUA
TC4428AEUA713
TC4428AVUA
TC4428AVUA713
TC4428CUA
TC4428CUA713
TC4428EUA
TC4428EUA713
TC4428VUA
TC4428VUA713